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Composition Table									
To:		TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.							
From:		Forehope Electronic (Ningbo) Co.,Ltd.							
Product Name:		TLSR8251F512ET48							
Weight(Unit):		128.2326 mg						Date:	2023/10/17
	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	0.9605	Silicon	7440-21-3	0.9605	100.00%	0.75%	1000000
Die2	GD Die	SMIC BJ	0.2167	Silicon	7440-21-3	0.2167	100.00%	0.17%	1000000
Lead Frame	C194	SHS	70.8226	Copper	7440-50-8	68.6979	97.00%	55.57%	970000
				Silver	7440-22-4	0.2479	0.35%	0.19%	3500
				Iron	7439-89-6	1.6997	2.40%	1.33%	24000
				Zinc	7440-66-6	0.1062	0.15%	0.08%	1500
				Phosphorus	7723-14-0	0.0708	0.10%	0.06%	1000
DAF	ATB-F125	Henkel	0.0192	Silicon dioxide	7631-86-9	0.0106	55.0%	0.01%	550000
				Modified epoxy resin	Trade Secret	0.0048	25.0%	0.00%	250000
				Poly[oxy[(2-oxiranyl)-1,2-cyclohexanediyl]], a-hydro-w-hydroxy-, ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1)	244772-00-7	0.0015	8.0%	0.00%	80000
				Phenol-formaldehyde polymer	9003-35-4	0.0015	8.0%	0.00%	80000
				bisphenol-A-(epichlorhydrin)	25068-38-6	0.0008	4.0%	0.00%	40000
Epoxy	503CuM	理均	0.1833	Diethylene glycol monoethyl ether acetate	112-15-2	0.0084	4.6000%	0.01%	46000
				Silver flake	7440-22-4	0.1430	78.0000%	0.11%	780000
				Acylate resin	Proprietary	0.0147	8.0000%	0.01%	80000
				Epoxy resin	Proprietary	0.0165	9.0000%	0.01%	90000
				Peroxide	Proprietary	0.0007	0.4000%	0.00%	4000
Wire	R2SS	乐金	0.6018	Silver	7440-22-4	0.5747	95.5000%	0.45%	955000
				Palladium	7440-05-3	0.0271	4.5000%	0.02%	45000
Mold Compound	G630	Sumitomo	52.3325	Epoxy Resin A	Trade Secret	1.0467	2.00%	40.81%	20000
				Epoxy Resin B	Trade Secret	1.0467	2.00%	0.82%	20000
				Phenol Resin	Trade Secret	3.6633	7.00%	2.86%	70000
				Silica(Amorphous)A	Trade Secret	41.8660	80.00%	32.65%	800000
				Silica(Amorphous)B	60676-86-0	3.1400	6.00%	2.45%	60000
				Metal Hydroxide	Trade Secret	1.3083	2.50%	1.02%	25000
				Carbon Black	1333-86-4	0.2617	0.50%	0.20%	5000
Plating	TIN	YunNan Tin	3.0960	Tin	7440-31-5	3.0957	99.99%	2.41%	999900
				other	Trade secret	0.0003	0.01%	0.00%	100
Total			128.2326			128.2326	100%	1000000	

保存年限：三年  
051-A1  
保存单位：QRA

文件编号：TFM-QRA-